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Amdt
J. McNeill
9/11/02

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DATE: September 6, 2002

TO: U.S. Patent and Trademark Office - Group Art Unit 2827
Attention: Examiner T. Blum

FROM: W. Kevin Ransom

* * * **OFFICIAL** * * *

In re:	Stemmons et al.	Confirmation No.:	9245
Appl. No.:	10/005,633	Group Art Unit:	2827
Filed:	December 5, 2001	Examiner:	D. Gaybill
For:	MICROBEAM ASSEMBLY FOR INTEGRATED CIRCUIT INTERCONNECTION TO SUBSTRATES		

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(Including cover page)

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Attorney's Docket No. 038190/241788

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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Commissioner for Patents
Washington, DC 20231

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AMENDMENT

Sir:

In response to the Office Action mailed June 6, 2002, please amend the above-identified application as follows:

In The Claims:

Please cancel claims 29 and 33 and amend Claims 25, 26, and 30 as follows:

25. A microbeam assembly adapted to form interconnects between integrated circuit bond pads and substrate contacts, the microbeam assembly comprising:

a carrier;

a plurality of conductive microbeams releasably bonded to the carrier, wherein the conductive microbeams are sized and spaced to mate with the bond pads of an integrated circuit, and wherein at least one of said conductive microbeams comprises solder coating a portion thereof;

a solder dam positioned on a surface of said at least one conductive microbeam comprising solder opposite said carrier, said solder dam for preventing solder from wetting along a portion of said microbeam not coated with solder; and

a release layer positioned between said carrier and said conductive microbeams for releasably supporting the conductive microbeams.

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